

## Final Product/Process Change Notification Document #:FPCN23749ZA Issue Date:29 Apr 2022

Title of Change:	Wafer Fab Transfer to onsemi Pocatello, ID USA from Fab2 Oudenaarde, Belgium Related to Fab2 Oudenaarde sale - Continental Special [Batch 1]			
Proposed Changed Material First Ship Date:	01 Nov 2022 or earlier if approved by customer			
Current Material Last Order Date:	30 Jun 2021 This date was carried forward from IPCN23749ZA Orders received after the Current Material Last Order Date expiration are to be considered a orders for new changed material as described in this PCN. Orders for current (unchanged material after this date will be per mutual agreement and current material inventory availability			
Current Material Last Delivery Date:	31 Oct 2022 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory			
Product Category:	Active components – Discrete components			
Contact information:	Contact your local onsemi Sales Office or Noor	Contact your local onsemi Sales Office or NoorArdila.Shaharuddin@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.			
Sample Availability Date:	18 Apr 2022			
PPAP Availability Date:	31 May 2022			
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com			
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.			
Change Category				
Category	Type of Change			
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter			
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.			
Description and Purpose:	mers of wafer fab site transfer from Fab2, Oudena	rrde, Belgium onsemi Pocatello, USA.		
The final change notification is to inform custor				
The final change notification is to inform custon	From	То		
The final change notification is to inform custon Fab Site	From Fab2,Oudenarrde (Belgium)	<b>To</b> onsemi, Pocatello Idaho (USA)		

Affected parts with this change will be identified by date code.



-	ivation for Change:	Acquisition				
unction, relia	ıpact on fit, form, bility, product ufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.				
ites Affected:						
onsemi Sites				External Foundry/Subcon Site	es	
onsemi Pocatello Idaho, United States		None				
Marking of Parts/ Traceability of Change:			th this chang	rowill be identified by data and		
Change: Reliability Dat QV DEVICE NAM						
Change: Reliability Dat RV DEVICE NAM RMS PACKAGE	a Summary: /IE : SESD9L5.0ST5G : L76922 : SOD923				Interval	Populto
Change: Reliability Dat RV DEVICE NAM MS PACKAGE Test	a Summary: //E : SESD9L5.0ST5G : L76922 : SOD923 Specification			Condition	Interval 2016 brs	Results
change: celiability Dat to DEVICE NAM MS ACKAGE <u>Test</u> HTRB	a Summary: AE : SESD9L5.0ST5G : L76922 : SOD923 Specification JESD22-A108			Condition 150°C, 100% max rated V	2016 hrs	0/231
Change: Reliability Dat RV DEVICE NAM MS PACKAGE Test HTRB HTSL	a Summary: AE : SESD9L5.0ST5G : L76922 : SOD923 Specification JESD22-A108 JESD22-A103		Ta = 1	Condition 150°C, 100% max rated V Ta = 150°C	2016 hrs 2016 hrs	0/231 0/231
Change: Reliability Dat RV DEVICE NAM MS PACKAGE Test HTRB HTRL TC	a Summary: AE : SESD9L5.0ST5G : L76922 : SOD923 Specification JESD22-A108 JESD22-A103 JESD22-A104		 Ta = 1 	Condition           150°C, 100% max rated V           Ta = 150°C           Ta = -65°C to +150°C	2016 hrs 2016 hrs 1000 cyc	0/231 0/231 0/231
Change: Reliability Dat RV DEVICE NAM MS PACKAGE Test HTRB HTSL TC HAST	A Summary: AE : SESD9L5.0ST5G : L76922 : SOD923 Specification JESD22-A108 JESD22-A103 JESD22-A104 JESD22-A110		Ta = 1 130°C	Condition           150°C, 100% max rated V           Ta = 150°C           Fa = -65°C to +150°C           C, 85% RH, 18.8psig, bias	2016 hrs 2016 hrs 1000 cyc 192 hrs	0/231 0/231 0/231 0/231
Change: Reliability Dat OV DEVICE NAM MS PACKAGE Test HTRB HTRL TC	a Summary: AE : SESD9L5.0ST5G : L76922 : SOD923 Specification JESD22-A108 JESD22-A103 JESD22-A104		Ta = 1 130°C	Condition           150°C, 100% max rated V           Ta = 150°C           Ta = -65°C to +150°C	2016 hrs 2016 hrs 1000 cyc	0/231 0/231 0/231

1. Download pdf copy of the PCN to your computer

2. Open the downloaded pdf copy of the PCN

3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field

4. Then click on the attached file/s

## **Electrical Characteristics Summary:**

Electrical characteristics are not impacted.

## List of Affected Parts:

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
SESD9L5.0ST5G	NA	SESD9L5.0ST5G



## Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
SESD9L5.0ST5G		SESD9L5.0ST5G	NA	